

High Current Density Surface-Mount TMBS[®] (Trench MOS Barrier Schottky) Rectifier

 Ultra Low $V_F = 0.54$ V at $I_F = 2.5$ A


FEATURES

- Very low profile - typical height of 1.3 mm
- Trench MOS Schottky technology
- Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
- Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

 AUTOMOTIVE
GRADE
Available

RoHS
COMPLIANT
HALOGEN
FREE

LINKS TO ADDITIONAL RESOURCES



TYPICAL APPLICATIONS

For use in low voltage high frequency DC/DC converters, freewheeling diodes, and polarity protection applications.

MECHANICAL DATA

Case: SlimDPAK (TO-252AE)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	2 x 5 A
V_{RRM}	120 V
I_{FSM}	80 A
V_F at $I_F = 5$ A ($T_J = 125$ °C)	0.63 V
T_J max.	175 °C
Package	SlimDPAK (TO-252AE)
Circuit configuration	Common cathode

MAXIMUM RATINGS ($T_A = 25$ °C unless otherwise noted)			
PARAMETER	SYMBOL	V10PWM12C	UNIT
Device marking code		V10PWM12C	
Maximum repetitive peak reverse voltage	V_{RRM}	120	V
Maximum average forward rectified current (Fig. 1)	$I_{F(AV)}$ ⁽¹⁾	per device	10
		per diode	5
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load per diode	I_{FSM}	80	A
Operating junction temperature range	T_J ⁽²⁾	-40 to +175	°C
Storage temperature range	T_{STG}	-55 to +175	°C

Notes

⁽¹⁾ With infinite heatsink

⁽²⁾ The heat generated must be less than the thermal conductivity from junction to ambient: $dP_D/dT_J < 1/R_{\theta JA}$



ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage per diode	$I_F = 2.5\text{ A}$	$T_J = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.64	-	V
	$I_F = 5\text{ A}$			0.78	0.86	
	$I_F = 2.5\text{ A}$	$T_J = 125\text{ }^\circ\text{C}$		0.54	-	
	$I_F = 5\text{ A}$			0.63	0.7	
Reverse current per diode	$V_R = 90\text{ V}$	$T_J = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	0.0003	-	mA
		$T_J = 125\text{ }^\circ\text{C}$		0.5	-	
	$V_R = 120\text{ V}$	$T_J = 25\text{ }^\circ\text{C}$		-	0.15	
		$T_J = 125\text{ }^\circ\text{C}$		1	5	
Typical junction capacitance per diode	4.0 V, 1 MHz		C_J	420	-	pF

Notes

- (1) Pulse test: 300 μs pulse width, 1 % duty cycle
(2) Pulse test: pulse width $\leq 5\text{ ms}$

THERMAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	V10PWM12C	UNIT
Typical thermal resistance per device	$R_{\theta JA}^{(1)(2)}$	65	$^\circ\text{C/W}$
	$R_{\theta JM}^{(3)}$	2.1	

Notes

- (1) The heat generated must be less than thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
(2) Free air, mounted on recommended copper pad area; thermal resistance $R_{\theta JA}$ - junction to ambient
(3) Mounted on infinite heat sink; thermal resistance $R_{\theta JM}$ - junction-to-mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V10PWM12C-M3/I	0.20	I	4500	13" diameter plastic tape and reel
V10PWM12CHM3/I ⁽¹⁾	0.20	I	4500	13" diameter plastic tape and reel

Note

- (1) AEC-Q101 qualified

RATINGS AND CHARACTERISTICS CURVES ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

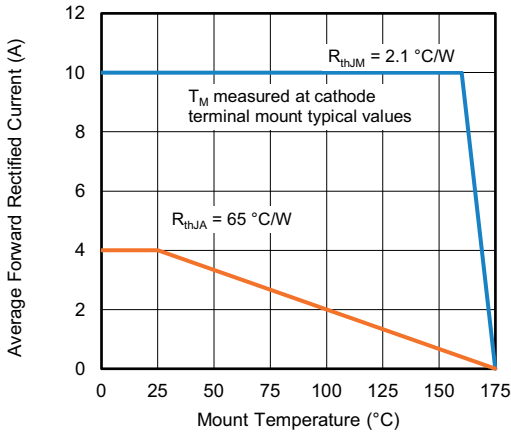


Fig. 1 - Maximum Forward Current Derating Curve

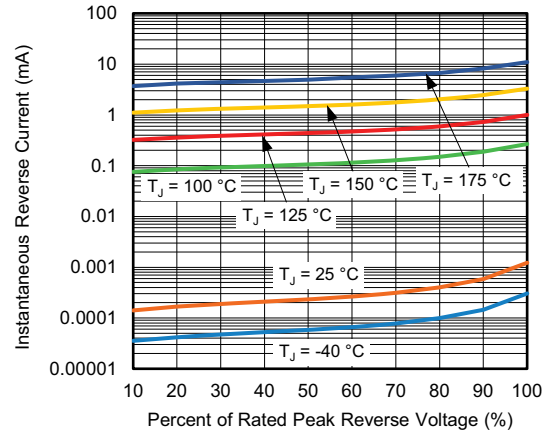


Fig. 4 - Typical Reverse Leakage Characteristics Per Diode

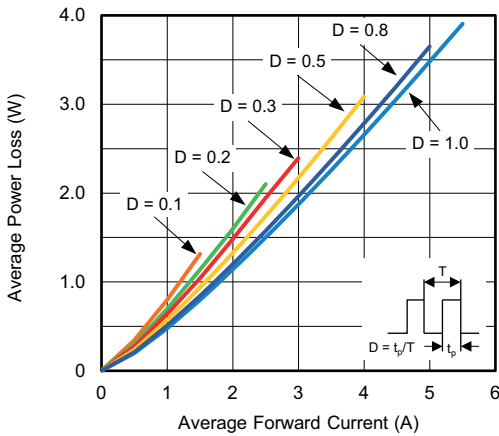


Fig. 2 - Forward Power Loss Characteristics Per Diode

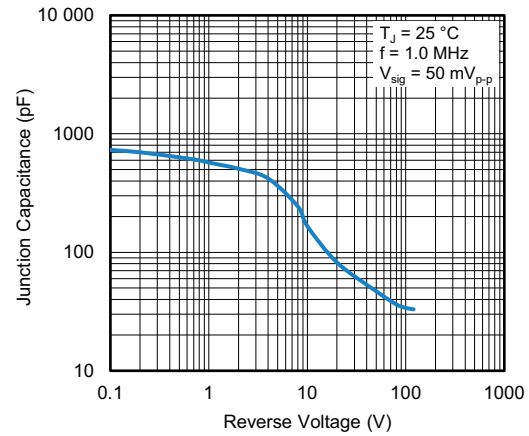


Fig. 5 - Typical Junction Capacitance Per Diode

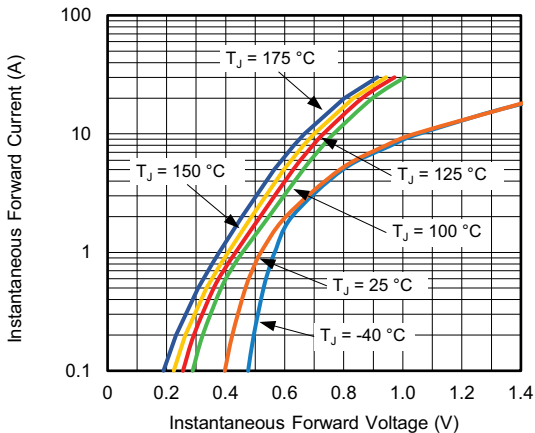


Fig. 3 - Typical Instantaneous Forward Characteristics Per Diode

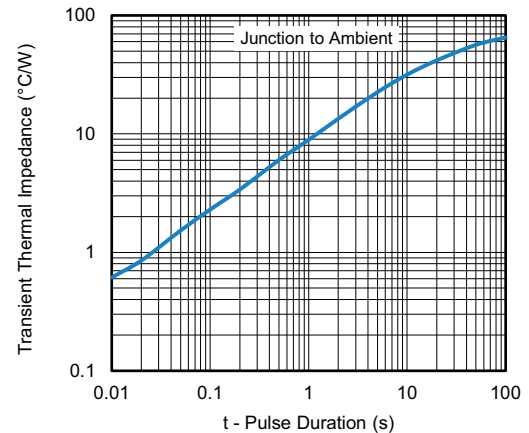


Fig. 6 - Typical Transient Thermal Impedance

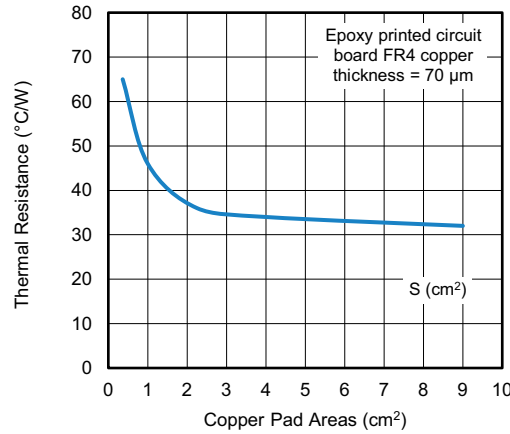
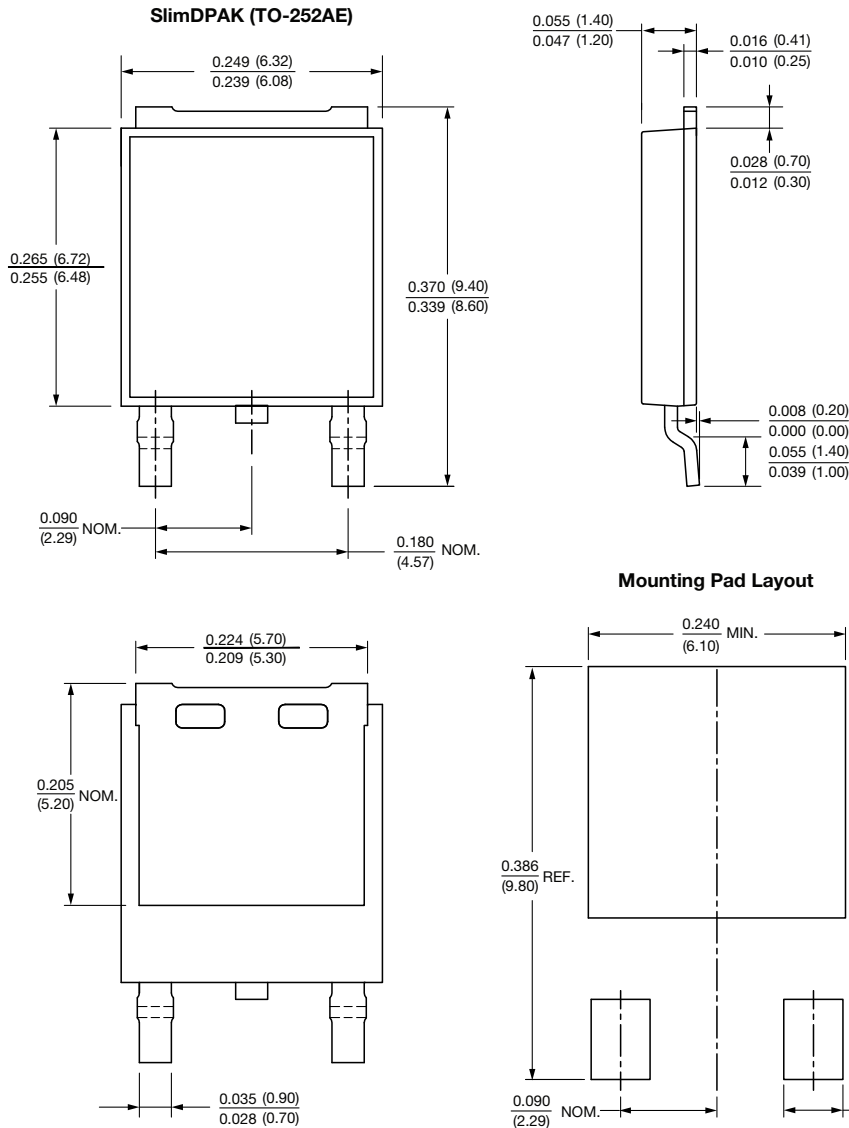


Fig. 7 - Typical Resistance Junction to Ambient vs. Copper Pad Areas

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)





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